

Preliminary Amendment

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Title: **NON-LEADED SEMICONDUCTOR PACKAGE AND A METHOD TO ASSEMBLE THE SAME**

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

**NON-LEADED SEMICONDUCTOR PACKAGE AND A METHOD TO ASSEMBLE
THE SAME**

Abstract

A method to assemble a non-leaded semiconductor package (1) comprises the following steps disclosed. In one embodiment, A carrier tape (43) is attached to a metal foil (42). A plurality of leadframes (3) are formed in the metal foil (42), each leadframe (3) comprising including a die pad (4) laterally surrounded by a plurality of contact leads (5). A semiconductor die (2), including an active surface with a plurality of die contact pads (6), is attached to each die attach pad (4) and electrically connected to the leadframe (3) by a plurality of bond wires (9) connecting the die contact pads (6) and the lead contact areas (6) of the contact leads (5). A plurality of leadframes (3), each including a wire bonded semiconductor die, are encapsulated with mold material (40). The carrier tape (43) is removed and the non-leaded semiconductor packages (1) separated.

{FIGS. 5}